

**HYSOL GR 600 (LMC20576-10P1)**

June 2018

PRODUCT DESCRIPTION

HYSOL GR 600 (LMC20576-10P1) is a green, semiconductor grade mold compound providing the following product characteristics:

Technology	Epoxy
Cure	Heat cure
Appearance	Black
Filler Type	Silica
Filler Weight, %	88 ±1
Application	Mold Compound
Target Package	Power module
Product Benefits	<ul style="list-style-type: none">• Green product• Delam-free• Low moisture absorption
Flammability Rating	UL 94 V0 @ 1/8 inch thickness

HYSOL GR 600 (LMC20576-10P1) is a green epoxy-based molding compound designed for power module package applications.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Spiral Flow, @175°C, inches	25
Gel Time, @175°C, seconds	36
Shelf Life, @ 5°C, days	183
Specific Gravity	2.11

TYPICAL PROCESS DATA

Handling	Typical Value
Preheat Temperature, conventional mold, °C	70~90
Molding Temperature, °C	170~190
Transfer Pressure, Kg/cm ²	40~85
Transfer Time @ 175°C, seconds	5~15
Hot Hardness, Shore D @ 175 °C, after 90sec	80
Curing Time @ 175 °C, seconds	120
Post Mold Cure @ 175 °C, hours	4~8

HYSOL GR 600 (LMC20576-10P1) has been formulated to provide the best possible moldability and as wide a molding latitude as possible. Although molding and curing conditions will vary from situation to situation, recommended starting ranges are shown above.

Please contact Hysol Huawei Technical Service for alternative process parameters if needed.

TYPICAL PROPERTIES OF CURED MATERIAL

All measurements are taken at 25°C unless otherwise noted.

All physical, electrical and analytical measurements are taken on specimens cured for **120** seconds @ **175°C** with post cure of 6 hours @ **175°C**, unless otherwise specified.

Physical Properties

Property	Typical Value
Glass Transition Temperature, °C: (Tg) via TMA	124
Coefficient of Thermal Expansion, TMA, ppm/°C: Below Tg	14
Above Tg	36
Flexural Modulus @ 25°C	19,843 (N/mm ²)
Flexural Strength @ 25°C	142 (N/mm ²)
DMA Modulus: @ 25 °C	25,750 (N/mm ²)
@ 175 °C	1.312 (N/mm ²)
@ 260 °C	863 (N/mm ²)
Moisture Absorption, 24 hours PCT, %	0.22
Thermal Conductivity @ W/(m-K)	1.41

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

Not for product specifications

The technical data contained herein are intended as reference only. Please contact Hysol Huawei Electronics Co., Ltd. quality department for assistance and recommendations on specifications for this product

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: -18°C or below, in closed containers. After removal from cold storage, the material **MUST** be allowed to come to room temperature, in the sealed container, to avoid moisture contamination. The suggested waiting time for a standard 15 kg carton box is 24 hours.

Material removed from containers may be contaminated during use. Do not return product to the original container. Hysol Huawei Electronics Co., Ltd. cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact Hysol Huawei Electronics Co., Ltd. Technical Service or Customer Service Representative.

**Disclaimer
NOTE**

The information provided in this Laboratory Data Sheet (LDS) including the recommendations for use and application of the product are based on our best knowledge and experience of the product as at the date of this LDS.

Hysol Huawei Electronics Co., Ltd. is, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

Any liability in respect of the information in the Laboratory Data Sheet regarding the concerned product is excluded.